

## Reflow oven RK360



- **Reflow oven RK 360**

- **Technical data**

- **Infrared + Air circulation + Air cooling, Pb-free Reflow Oven**

- Surface mounting of units on boards require the exposure of the device package to high temperature to melt the lead finish for board soldering. A lot of the alternative "lead-free" solder materials being considered for use in IC assembly today require a peak soldering temperature of about 250 to 260 deg C, versus the peak temperature of 230 to 235 deg C for Sn-Pb solder. This means that lead-free IC's will need a higher temperature for board mounting, and will therefore be subjected to more severe thermo-mechanical stresses during the process.
- This Oven feature a complete system for today's solder/ Pb-Free solder(300C) requirement. The computer control 20 step range (20 Zone) temperature control allow a smooth and well control temperature curve. High power heating element with force air heating method provide a very even soldering hot zone across the total soldering area, This cost effective unit offer high production count ( 4~5 mins per cycle of 300mm x 220mm board) which ideal for low to medium size of SMD production. The static soldering process offer very stable non moving especially important for fine pitch SMD soldering.

- **Features:**

- Infrared Array + Force Air ( high volume, low pressure ) Heating Method.
- Programmable 20 step control for temperature curve setting.
- Internal cooling fan for fast Cool down performance.
- Fully Automatic, fully static ( non moving rail) operation, single or double side board soldering.
- Large transparent glass window see throught the soldering process with high temperature build in 35W light ( separated ON/OFF) switch.
- Internal complete high gloss stainless steel construction, high IR efficiency and easy to clean, maintenance.
- Ball bearing Rail draw system for stable solder board exchange with minimum vibration.
- Optional PCB tray for quick exchange between the board process.
- Top Open design for quick access to heating element and service.
- Dual channel air circulation. For fast cool down process.

- **Specifications:**

- Maximum heating area: 320mm x 220mm
- Interchangeable tray for continuous process.
- Maximum Temperature: 300C
- Power supply: AC220V/50Hz
- Maximum Power consumption: 3.5kW, 1,2kW Typ.
- Weight: 50kg
- Dimension: 565 x 600 x 500 mm